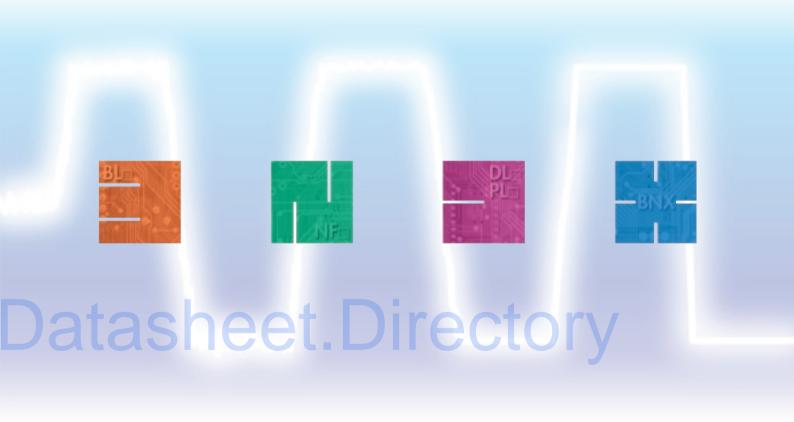
SMD/BLOCK Type EMI Suppression Filters







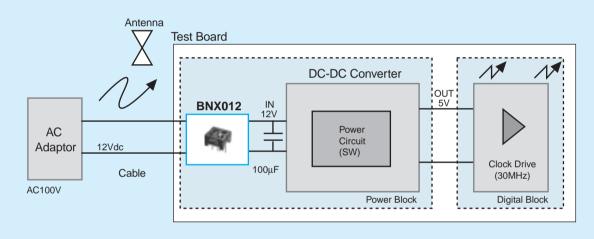
Block Type EMIFIL®

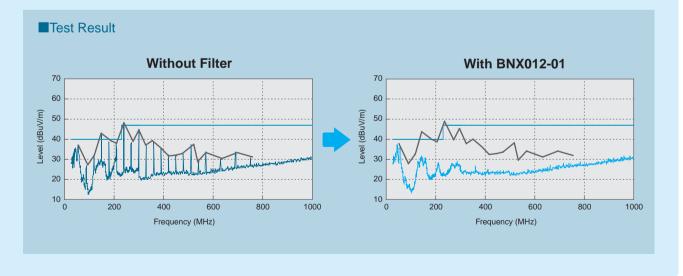
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Туре	Part Number	Thickness (mm)	Rated Voltage	Effective Frequency Range	Rated Current	Kit ≧3A Flow ReFlow
p191	BNX022-01	3.1	50Vdc	1MHz to 1GHz:35dB min.	10A	Kit ≧3A ReFlow
SMD Type	BNX023-01	3.1	100Vdc	1MHz to 1GHz:35dB min.	15A	Kit ≧3A ReFlow
for Power Lines	BNX024H01	3.5	50Vdc	100kHz to 1GHz:35dB min.	15A	Kit ≧3A ReFlow
	BNX025H01	3.5	25Vdc	50kHz to 1GHz:35dB min.	15A	Kit ≧3A ReFlow
Lood Typo	BNX002-01	18.0	50Vdc	1MHz to 1GHz:40dB min.	10A	Kit ≧3A Flow
Lead Type for Power Lines	BNX003-01	18.0	150Vdc	5MHz to 1GHz:40dB min.	10A	Kit ≧3A Flow
ioi Fower Lines	BNX005-01	18.5	50Vdc	1MHz to 1GHz:40dB min.	15A	Kit ≧3A Flow
Lead Type p194	BNX012-01	8.0	50Vdc	1MHz to 1GHz:40dB min.	15A	Kit ≧3A Flow
Low Profile for Power Lines	BNX016-01	8.0	25Vdc	100kHz to 1GHz:40dB min.	15A	Kit ≧3A Flow

Noise Suppression of Radiation Noise from Power Line Cable





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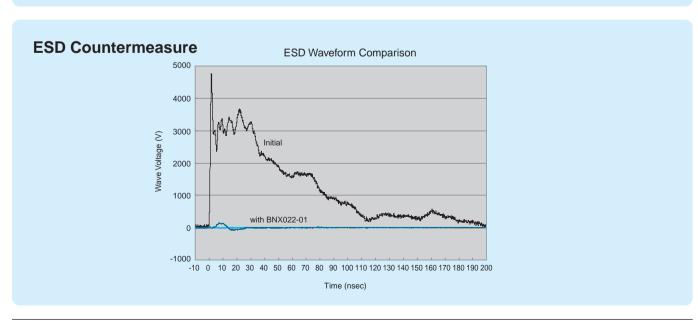
[•] This catalog has only typical specifications because there is no space for detailed specifications. Therefore, please review our product specifications or consult the approval sheet for product specifications before ordering.

Impulse Noise Countermeasure +B СВ Impulse Noise M 60dB Oscilloscope: Generator: (40dB+20dB) INS-4420 TDS7254 ATT (4kV, 50nsec) PSG CG **BNX ■**Without Filter Applied Impulse Voltage: 4kV/50nS Y-AXIS: 1kV/div **■**With Filter

1kV/Div1

1kV/Div1

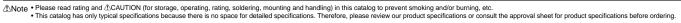
BNX022-01



BNX012-01

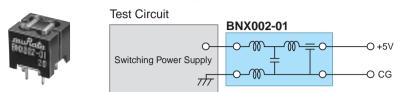
1kV/Div1

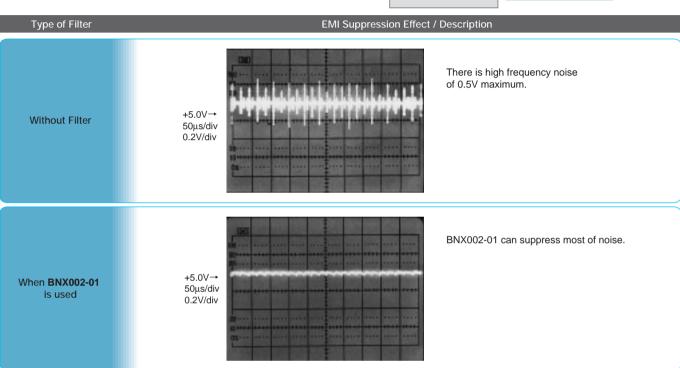
BNX002-01



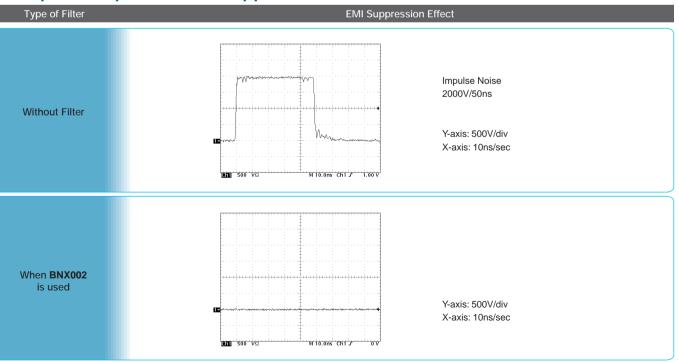


Suppression of Ripple Noise of DC Side in the Switching Power Supply

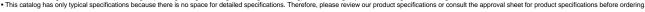




Example of Impulse Noise Suppression



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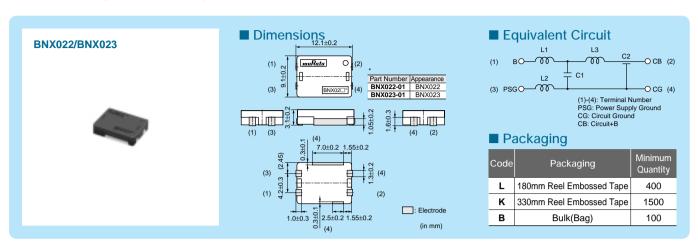


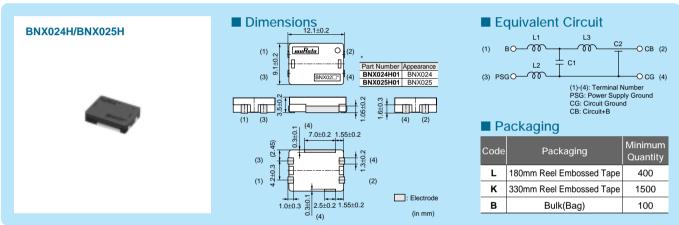


BNX02



SMD package of block type EMIFIL®.





Refer to pages from p.197 to p.200 for mounting information.

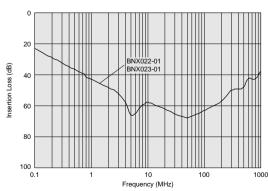
■ Rated Value (□: packaging code)

	Part Number	Rated Voltage	Withstand Voltage	Rated Current	Insulation Resistance (min.)	Insertion Loss (20 to 25 degrees C line impedance=50 ohm)	
Ī	BNX022-01□	50Vdc	125Vdc	10A	500M ohm	1MHz to 1GHz:35dB min.	Kit ≧3A
	BNX023-01□	100Vdc	250Vdc	15A	500M ohm	1MHz to 1GHz:35dB min.	Kit ≧3A
	BNX024H01□	50Vdc	125Vdc	15A	100M ohm	100kHz to 1GHz:35dB min.	Kit ≧3A
	BNX025H01□	25Vdc	62.5Vdc	15A	50M ohm	50kHz to 1GHz:35dB min.	Kit ≧3A

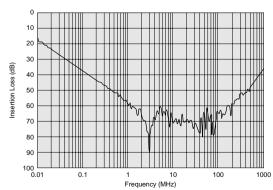
Operating Temperature Range: -40°C to +125°C (BNX022/BNX023), -55°C to +125°C (BNX024H/BNX025H)

■ Insertion Loss Characteristics

BNX022/023



BNX024H01



Continued on the following page.

Note • Please read rating and

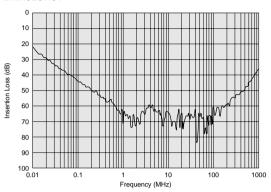
CAUTION (for storage, operating, rating, soldering, mounting and handling) in this catalog to prevent smoking and/or burning, etc.

• This catalog has only typical specifications because there is no space for detailed specifications. Therefore, please review our product specifications or consult the approval sheet for product specifications before order.



■ Insertion Loss Characteristics

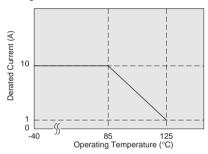
BNX025H01



■ Notice (Rating)

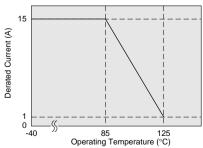
In operating temperatures exceeding +85°C, derating of current is necessary for BNX022 series. Please apply the derating curve shown in chart according to the operating temperature.

Derating



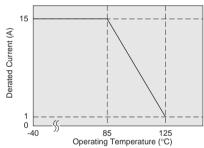
In operating temperatures exceeding +85°C, derating of current is necessary for BNX024H/025H series. Please apply the derating curve shown in chart according to the operating temperature.

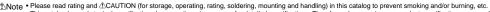
Derating

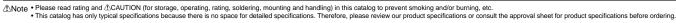


In operating temperatures exceeding +85°C, derating of current is necessary for BNX023 series. Please apply the derating curve shown in chart according to the operating temperature.

Derating





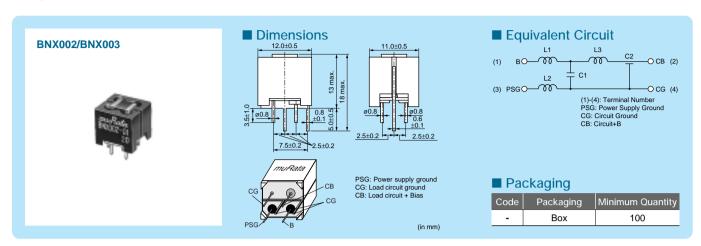


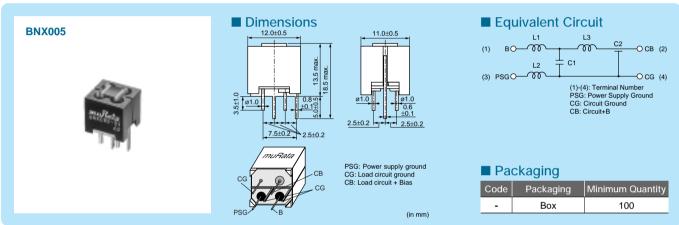
BNX00 Series





Large insertion loss from several hundred kHz to several GHz.





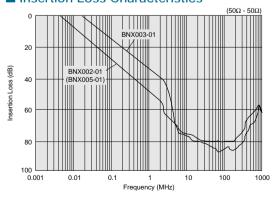
Refer to pages from p.197 to p.200 for mounting information.

■ Rated Value

Part No	lumber	Rated Voltage	Withstand Voltage	Rated Current	Insulation Resistance (min.)	Insertion Loss (20 to 25 degrees C line impedance=50 ohm)	
BNX0	002-01	50Vdc	125Vdc	10A	100M ohm	1MHz to 1GHz:40dB min.	Kit ≧3A
BNX0	003-01	150Vdc	375Vdc	10A	100M ohm	5MHz to 1GHz:40dB min.	Kit ≧3A
BNX0	005-01	50Vdc	125Vdc	15A	100M ohm	1MHz to 1GHz:40dB min.	Kit ≧3A

Operating Temperature Range: -30°C to +85°C

Insertion Loss Characteristics



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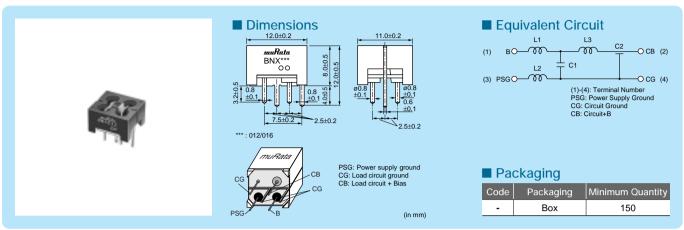


BNX01





Low profile version of BNX series.



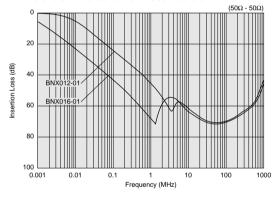
Refer to pages from p.197 to p.200 for mounting information.

■ Rated Value

Part Number	Rated Voltage	Withstand Voltage	Rated Current	Insulation Resistance (min.)	Insertion Loss (20 to 25 degrees C line impedance=50 ohm)	
BNX012-01	50Vdc	125Vdc	15A	500M ohm	1MHz to 1GHz:40dB min.	Kit ≧3A
BNX016-01	25Vdc	62.5Vdc	15A	50M ohm	100kHz to 1GHz:40dB min.	Kit ≧3A

Operating Temperature Range: -40°C to +125°C

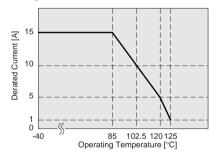
■ Insertion Loss Characteristics



■ Notice (Rating)

In operating temperatures exceeding +85°C, derating of current is necessary for BNX01□ series. Please apply the derating curve shown in chart according to the operating temperature.

Derating



■ Connecting ± power line In case of using \pm power line, please connect to each terminal as shown.

Power Supply	BN.	X		Circuit
(BNX Input)				(BNX Output)
Power Supply +Bias - Power Supply Ground -	В	СВ	-	Load Circuit +Bias
Power Supply Ground -	PSG	CG	-	Load Circuit Ground
Power Supply -Bias -	В	CB	-	Load Circuit -Bias
Power Supply -Bias - Power Supply Ground -	PSG	CG	-	Load Circuit Ground

Rating

Do not use products beyond the rated current and rated voltage as this may create excessive heat and deteriorate the insulation resistance.

Notice

Storage and Operating Conditions

<Operating Environment>

Do not use products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

Do not use products in the environment close to the organic solvent.

- <Storage and Handling Requirements>
- 1. Storage Period BNX series should be used within 12 months. Solderability should be checked if this period is exceeded.
- 2. Storage Conditions
- (1) Storage temperature: -10 to +40°C Relative humidity: 15 to 85% Avoid sudden changes in temperature and humidity.
- (2) Do not store products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

Notice (Soldering and Mounting)

1. Cleaning

Do not clean BNX series (SMD Type). Before cleaning, please contact Murata engineering.

Reliability decreases with improper soldering methods. Please solder by the standard soldering conditions shown in mounting information.

Noise suppression levels resulting from Murata's EMI conditions. Be sure to check and confirm in advance the noise suppression effect of each filter, in actual circuits, etc. before applying the filter in a commercialpurpose equipment design.

Handling

1. Resin Coating

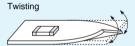
Using resin for coating/molding products may affect the products performance.

So please pay careful attention in selecting resin. Prior to use, please make the reliability evaluation with the product mounted in your application set.

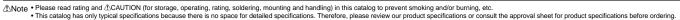
2. Handling of a Substrate (for BNX02□) After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate.

Excessive mechanical stress may cause cracking in the Product.

Bending



suppression filters EMIFIL® may vary, depending on the circuits and ICs used, type of noise, mounting pattern, mounting location, and other operating







∴ Caution/Notice **Block Type EMIFIL® Lead Type**

Rating

Do not use products beyond the rated current and rated voltage as this may create excessive heat and deteriorate the insulation resistance.

Notice

Storage and Operating Conditions

<Operating Environment>

- 1. Do not use products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.
- 2. Do not use products near water, oil or organic solvents.
- <Storage and Handling Requirements>
- 1. Storage Period BNX Series should be used within 12 months. Solderability should be checked if this period is exceeded.
- 2. Storage Conditions
- (1) Storage temperature: -10 to +40°C Relative humidity: 15 to 85% Avoid sudden changes in temperature and humidity.
- (2) Do not store products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

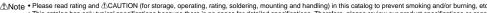
Notice (Soldering and Mounting)

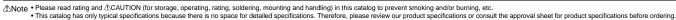
1. Cleaning

Failure and degradation of a product are caused by the cleaning method. When you clean in conditions that are not in mounting information, please contact Murata engineering.

- 2. Soldering
 - Reliability decreases with improper soldering methods. Please solder by the standard soldering conditions shown in mounting information.
- 3. Other

Noise suppression levels resulting from Murata's EMI suppression filters "EMIFIL" may vary, depending on the circuits and ICs used, type of noise, mounting pattern, lead wire length, mounting location, and other operating conditions. Be sure to check and confirm in advance the noise suppression effect of each filter, in actual circuits, etc. before applying the filter in a commercial-purpose equipment design.





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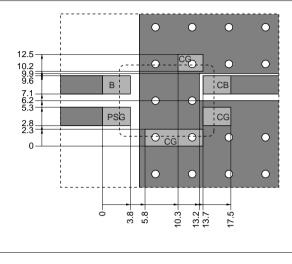


1. Standard Land Pattern Dimensions



(in mm)

BNX022 BNX023 BNX024 BNX025



- (1) A double-sided print board (or multilayer board) as shown in the left figure is designed, and please apply a soldering Cu electrode with a product electrode to a "Land Pattern", apply resist to a "Land Pattern + Solder Resist" at Cu electrode.
- (2) This product has large rated current of 10A/15A. Please consider real current and make Cu electrode thick enough. (Please design line resistance suitable for real current)
- (3) Please drop CG on a ground electrode on the back layer (the same also in a multilayer case) by the through hole. And a surface grand electrode layer may also take a large area as much as possible.
- (4) It is recommended to use a double-sided printed circuit board with BNX mounting on one side and the ground pattern on the other in order to maximize filtering performance, multiple feed through holes are required to maximize the BNX's connection to ground.
- (5) The ground pattern should be designed to be as large as possible to achieve maximum filtering performance.
- PCB Warping (for BNX02□) PCB should be designed so that products are not subjected to the mechanical stress caused by warping the board.

Products should be located in the sideways direction (Length: a<b) to the mechanical stress. Poor example Good example

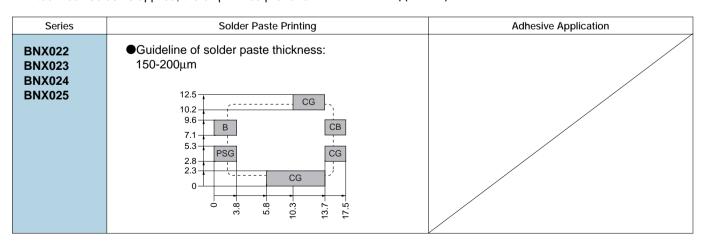
2. Solder Paste Printing and Adhesive Application

When reflow soldering the block type EMIFIL®, the printing must be conducted in accordance with the following cream solder printing conditions.

If too much solder is applied, the chip will be prone to

damage by mechanical and thermal stress from the PCB and may crack.

Standard land dimensions should be used for resist and copper foil patterns.



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3. Standard Soldering Conditions

(1) Soldering Methods

Use reflow soldering methods only.

Use standard soldering conditions when soldering block type EMIFIL® SMD type.

In cases where several different parts are soldered, each having different soldering conditions, use those conditions requiring the least heat and minimum time.

Solder: Use Sn-3.0Ag-0.5Cu solder. Use of Sn-Zn based solder will deteriorate performance of products.

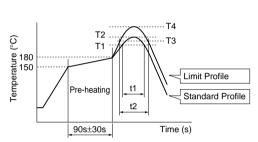
Flux:

- Use Rosin-based flux.
 In case of using RA type solder, products should be cleaned completely with no residual flux.
- Do not use strong acidic flux (with chlorine content exceeding 0.20wt%)
- Do not use water-soluble flux.

For additional mounting methods, please contact Murata.

(2) Soldering Profile

●Reflow Soldering Profile (Sn-3.0Ag-0.5Cu solder)



	Standard Profile					Limit	Profile	
Series	Hea	ting	Peak Temperature	Cycle	Heating		Peak Temperature	Cycle
	Temp. (T1)	Time. (t1)	(T2)	of Reflow	Temp. (T3)	Time. (t2)	(T4)	of Reflow
BNX022/023/024/025	220°C min.	30 to 60s	250±3°C	2 times max.	230°C min.	60s max.	260°C/10s	2 times max.

(3) Reworking with Solder Iron

The following conditions must be strictly followed when using a soldering iron.

Pre-heating: 150°C 60s min.

Soldering iron power output: 100W max.

Temperature of soldering iron tip / Soldering time / Times:

450°C max. / 5s max. / 1 time

Do not allow the tip of the soldering iron to directly contact the chip.

For additional methods of reworking with a soldering iron, please contact Murata engineering.

4. Cleaning

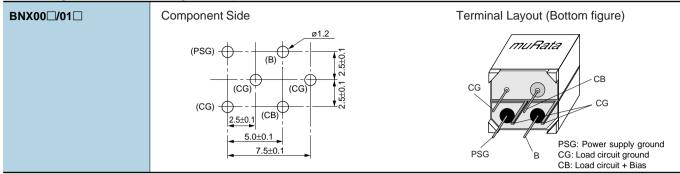
Do not clean BNX022/023/024/025 series. In case of cleaning, please contact Murata engineering.



BIOCK Type EMIFIL® Lead Type Soldering and Mounting

1. Mounting Hole

Mounting holes should be designed as specified below.



2. Using the Block Type EMIFIL® (Lead Type) Effectively

(1) How to use effectively

This product effectively prevents undesired radiation and external noise from going out / entering the circuit by grounding the high frequency components which cause noise problems. Therefore, grounding conditions may affect the performance of the filter and attention should be paid to the following for effective use.

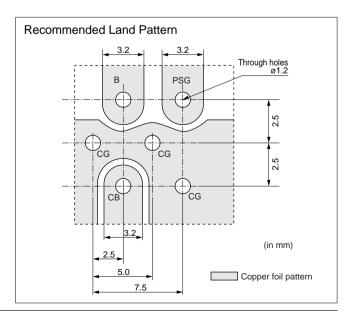
- (a) Design maximized grounding area in the P.C. board, and grounding pattern for all the grounding terminals of the product to be connected. (Please follow the specified recommendations.)
- (b) Minimize the distance between ground of the P.C. board and the ground plate of the product. (Recommend unsing the through hole connection between grounding area both of component side and bottom side.)
- (c) Insert the terminals into the holes on P.C. board completely.
- (d) Don't connect PSG terminal with CG terminal directly. (See the item 1. Terminal Layout)

(2) Self-heating

Though this product has a large rated current, localized selfheating may be caused depending on soldering conditions. To avoid this, attention should be paid to the following:

- (a) Use P.C. board with our recommendation on hole diameter / land pattern dimensions, mentioned in the right hand drawing, especially for 4 terminals which pass current.
- (b) Solder the terminals to the P.C. board with soldercover area at least 90%. Otherwise, excess selfheating at connection between terminals and P.C. board may lead to smoke and / or fire of the product even when operating at rated current.
- (c) After installing this product in your product, please make sure the self-heating is within the rated current recommended.

P. C. Board Patterns Use a bilateral P.C. board. Insert the BNX into the P.C.board until the root of the terminal is secured, then solder. (1) Component Side View (2) Bottom View Shield plate β ВФ PSG + CG_® CG Copper foil pattern



Note • Please read rating and

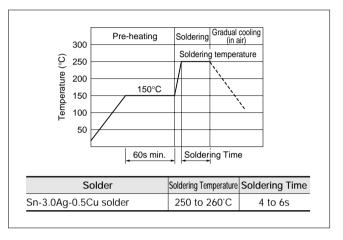
CAUTION (for storage, operating, rating, soldering, mounting and handling) in this catalog to prevent smoking and/or burning, etc.

This catalog has only typical specifications because there is no space for detailed specifications. Therefore, please review our product specifications or consult the approval sheet for product specifications before ordering.



3. Soldering

- (1) Use Sn-3.0Ag-0.5Cu solder.
- (2) Use Rosin-based flux. Do not use strong acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).
- (3) Products and the leads should not be subjected to any mechanical stress during the soldering process, or while subjected to the equivalent high temperatures.
- (4) Standard flow soldering profile



4. Cleaning

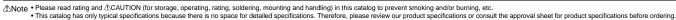
Clean the block Type EMIFIL® (Lead Type) in the following conditions.

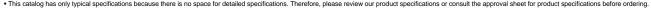
- (1) Cleaning temperature should be limited to 60°C max. (40°C max for alcohol type cleaner).
- (2) Ultrasonic cleaning should comply with the following conditions, avoiding the resonance phenomenon at the mounted products and P.C.B.

Power: 20W/liter max. Frequency: 28 to 40kHz Time: 5 min. max.

- (3) Cleaner
 - (a) Alcohol type cleaner Isopropyl alcohol (IPA)
 - (b) Aqueous agent Pine Alpha ST-100S

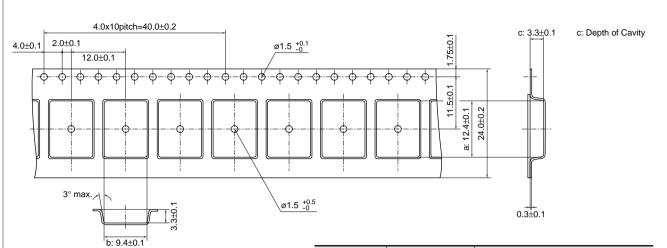
- (4) There should be no residual flux or residual cleaner left after cleaning.
 - In the case of using aqueous agent, products should be dried completely after rinsing with de-ionized water in order to remove the cleaner.
- (5) The surface of products may become dirty after cleaning, but there is no deterioration on mechanical, electrical characteristics and reliability.
- (6) Other cleaning: Please contact us.





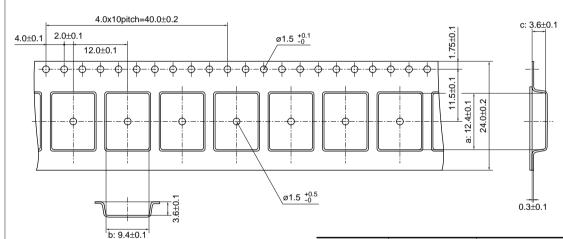
BIOCK Type EMIFIL® SMD Type Packaging

■ Minimum Quantity and Dimensions of 24mm Width Embossed Tape



Dimension of the cavity is measured at the bottom side.

Don't Niveshou	Ca	vity Si	ize	Minir	num Qty. (pcs.))
Part Number	а	b	С	ø180mm Reel	ø330mm Reel	Bulk
BNX022/023	12.4	9.4	3.3	400	1500	100

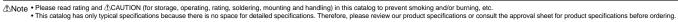


Dimension of the cavity is measured at the bottom side.

Dort Number	Ca	vity Si	ize	Minir	num Qty. (pcs.))
Part Number	a	b	С	ø180mm reel	ø330mm reel	Bulk
BNX024/025	12.4	9.4	3.6	400	1500	100

(in mm)

"Minimum Quantity" means the number of units of each delivery or order. The quantity should be an integral multiple of the "Minimum Quantity".





BIX Block Type EMIFIL® Design Kits



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●EKEPBNX0A

No.	Part Number	Quantity (pcs.)	Insertion Loss	Rated Voltage (Vdc)	Rated Current (A)
1	BNX002-01	1	1MHz to 1GHz : 40dB min.	50	10
2	BNX012-01	1	1MHz to 1GHz : 40dB min.	50	15
3	BNX016-01	1	100kHz to 1GHz : 40dB min.	25	15
4	BNX012H01	1	1MHz to 1GHz : 40dB min.	50	15
5	BNX022-01	3	1MHz to 1GHz : 35dB min.	50	10
6	BNX023-01	3	1MHz to 1GHz : 35dB min.	100	15
7	BNX024H01	3	100kHz to 1GHz : 35dB min.	50	15
8	BNX025H01	3	50kHz to 1GHz: 35dB min.	25	15

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No.	Part Number	Quantity (pcs.)	Insertion Loss	Rated Voltage (Vdc)	Rated Current (A)
1	BNX002-01	1	1MHz to 1GHz : 40dB min.	50	10
2	BNX003-01	1	5MHz to 1GHz : 40dB min.	150	10
3	BNX005-01	1	1MHz to 1GHz : 40dB min.	50	15
4	BNX012-01	1	1MHz to 1GHz : 40dB min.	50	15
5	BNX016-01	1	100kHz to 1GHz : 40dB min.	25	15
6	BNX012H01	1	1MHz to 1GHz : 40dB min.	50	15
7	BNP002-02	1	20MHz to 500MHz : 40dB min.	50	10
8	BNX022-01	3	1MHz to 1GHz : 35dB min.	50	10
9	BNX023-01	3	1MHz to 1GHz : 35dB min.	100	15
10	BNX024H01	3	100kHz to 1GHz : 35dB min.	50	15
11	BNX025H01	3	50kHz to 1GHz : 35dB min.	25	15